

Quarterly Reliability Monitoring Results

Quarters: Q1/2020 to Q4/2020

Based on structural similarity

Supplier		User Part Number				
Nexperia B.V.		PUSB3FA2				
Name of Laboratory		Part Description				
Assembly reliability labs		NXP ICN8 Protection INDI MCD package				
Test	Test Conditions	Duration	# Lots	# Quantity	# Rejects	
# 1	TEST Pre- and Post-Stress Electrical Test Tamb = 25 °C	N/A	see below	all parts	see below	
# 2	PC Preconditioning JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	115	9193	0	
# 5	HTRB High Temperature Reverse Bias MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	4	320	0	
# 7	TC Temperature Cycling JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	41	3299	0	
# 8	AC Autoclave JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	33	2640	0	
# 9	H3TRB High Humidity High Temperature Reverse Bias JESD22-A101 Tamb = 85 °C, RH = 85%, VR > 80 % of rated reverse voltage	1000 hours	41	3254	0	
# 10	IOL Intermittent Operating Life MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.	
# 20	RSH Resistance to Solder Heat JESD22-A111 260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.	
# 21	SD Solderability J-STD-002 Test method B and D		51	510	0	

Calculation of FIT and MTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
NXP ICN8	Protection INDI	320	0	13,27	7,54E+07

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